

Features

- Uses PingWei advanced PerfectMOS technology
- Extremely low on-resistance $R_{DS(on)}$
- Excellent $Q_g \times R_{DS(on)}$ product(FOM)
- Excellent Low Ciss
- Qualified according to JEDEC criteria

Benefits

- High robustness and reliability
- Increases maximum current capability
- Low power loss, high power density
- Easy paralleling

Applications

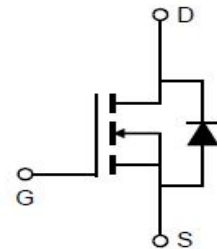
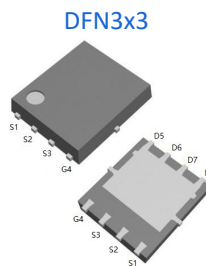
- Synchronous Rectification for AC/DC Quick Charger
- Battery management
- UPS (Uninterruptible Power Supplies)



100% DVDS Tested
100% Avalanche Tested

Product Summary

| | |
|-----------------------|-------|
| V_{DS} | 60V |
| $R_{DS(on)}@10V$ typ | 4.2mΩ |
| $R_{DS(on)}@4.5V$ typ | 5.8mΩ |
| I_D | 54A |



Package Marking and Ordering Information

| Part # | Marking | Package | Packing | Reel Size | Tape Width | Qty |
|-------------|-----------|---------|-----------|-----------|------------|---------|
| PW050N06HSL | 050N06HSL | DFN3*3 | Tape&Reel | 13 inches | 12mm | 5000pcs |

Absolute Maximum Ratings

| Parameter | Symbol | Value | Unit |
|---|----------------|------------|------------------|
| Drain-source voltage | V_{DS} | 60 | V |
| Continuous drain current | I_D | 73 | A |
| $T_C = 25^\circ\text{C}$ (Silicon limit) | | 54 | |
| $T_C = 25^\circ\text{C}$ (Package limit) | | 46 | |
| $T_C = 100^\circ\text{C}$ (Silicon limit) | | 12 | |
| $T_a = 25^\circ\text{C}$ | | | |
| Pulsed drain current ($T_C = 25^\circ\text{C}$) | $I_{D\ pulse}$ | 216 | A |
| Avalanche energy, single pulse (L=0.5mH) | E_{AS} | 56 | mJ |
| Gate-Source voltage | V_{GS} | ± 20 | V |
| Power dissipation | P_{tot} | 45 | W |
| $T_C = 25^\circ\text{C}$ | | 1.3 | |
| $T_a = 25^\circ\text{C}$ | | | |
| Operating junction and storage temperature | T_j, T_{stg} | -55...+150 | $^\circ\text{C}$ |
| Soldering temperature, wave soldering only allowed at leads (1.6mm from case for 10s) | T_{sold} | 260 | $^\circ\text{C}$ |

Thermal Resistance

| Parameter | Symbol | Value | | | Unit | Test Condition |
|--|--------|-------|------|------|------|----------------|
| | | min. | typ. | max. | | |
| Thermal resistance, junction – case. | RthJC | - | - | 2.8 | °C/W | - |
| Thermal resistance, junction - ambient(min. footprint) | RthJA | - | - | 98 | °C/W | - |

Electrical Characteristic (at Tj = 25 °C, unless otherwise specified)

| Parameter | Symbol | Value | | | Unit | Test Condition |
|-----------|--------|-------|------|------|------|----------------|
| | | min. | typ. | max. | | |

Static Characteristic

| | | | | | | |
|----------------------------------|--------------|-----|------------|------------|-----------|--|
| Drain-source breakdown voltage | BV_{DSS} | 60 | - | - | V | $V_{GS}=0V, I_D=250\mu A$ |
| Gate threshold voltage | $V_{GS(th)}$ | 1.2 | - | 2.5 | V | $V_{DS}=V_{GS}, I_D=250\mu A$ |
| Zero gate voltage drain current | I_{DSS} | - | - | 1 100 | μA | $V_{DS}=60V, V_{GS}=0V$ $T_j=25^\circ C$ $T_j=150^\circ C$ |
| Gate-source leakage current | I_{GSS} | - | - | ± 100 | nA | $V_{GS}=\pm 20V, V_{DS}=0V$ |
| Drain-source on-state resistance | $R_{DS(on)}$ | - | 4.2 5.8 | 5.0 7.5 | $m\Omega$ | $V_{GS}=10V, I_D=30A$ $V_{GS}=4.5V, I_D=30A$ |
| Transconductance | g_{fs} | - | 56 | - | S | $V_{DS}=5V, I_D=20A$ |

Dynamic Characteristic

| | | | | | | |
|------------------------------|--------------|---|------|---|----------|--|
| Input Capacitance | C_{iss} | - | 1927 | - | pF | $V_{GS}=0V, V_{DS}=30V,$ $f=1MHz$ |
| Output Capacitance | C_{oss} | - | 421 | - | | |
| Reverse Transfer Capacitance | C_{rss} | - | 39 | - | | |
| Gate Total Charge | Q_G | - | 35 | - | nC | $V_{DS}=30V, I_D=50A,$ $V_{GS}=10V$ |
| Gate-Source charge | Q_{gs} | - | 9.3 | - | | |
| Gate-Drain charge | Q_{gd} | - | 6.4 | - | | |
| Turn-on delay time | $t_{d(on)}$ | - | 9.5 | - | ns | $V_{GS}=10V, V_{DD}=30V,$ $R_{G_ext}=1.6\Omega, I_D=50A$ |
| Rise time | t_r | - | 43.6 | - | | |
| Turn-off delay time | $t_{d(off)}$ | - | 32.4 | - | | |
| Fall time | t_f | - | 13.5 | - | | |
| Gate resistance | R_G | - | 2.3 | - | Ω | $V_{GS}=0V, V_{DS}=0V,$ $f=1MHz$ |



Body Diode Characteristic

| Parameter | Symbol | Value | | | Unit | Test Condition |
|---------------------------------------|-------------|-------|------|------|------|-----------------------------|
| | | min. | typ. | max. | | |
| Body Diode Forward Voltage | V_{SD} | - | - | 1.2 | V | $V_{GS}=0V, I_{SD}=30A$ |
| Body Diode Continuous Forward Current | I_S | - | - | 54 | A | TC = 25°C |
| Body Diode Pulsed Current | I_S pulse | - | - | 216 | A | TC = 25°C |
| Body Diode Reverse Recovery Time | t_{rr} | - | 17 | - | ns | $I_F=50A, dI/dt=100A/\mu s$ |
| Body Diode Reverse Recovery Charge | Q_{rr} | - | 3.4 | - | nC | |

Typical Performance Characteristics

Fig 1: Output Characteristics

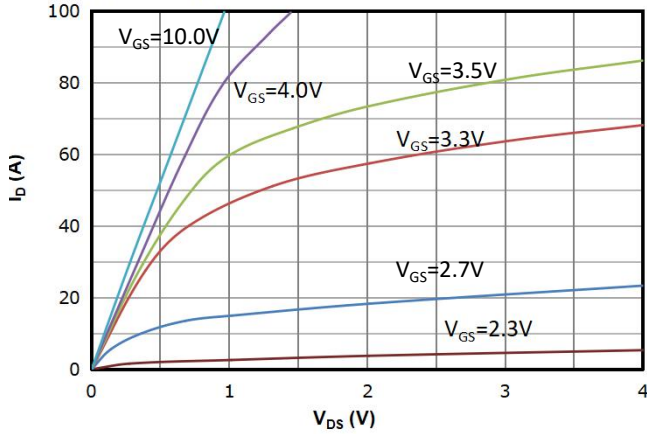


Fig 2: Transfer Characteristics

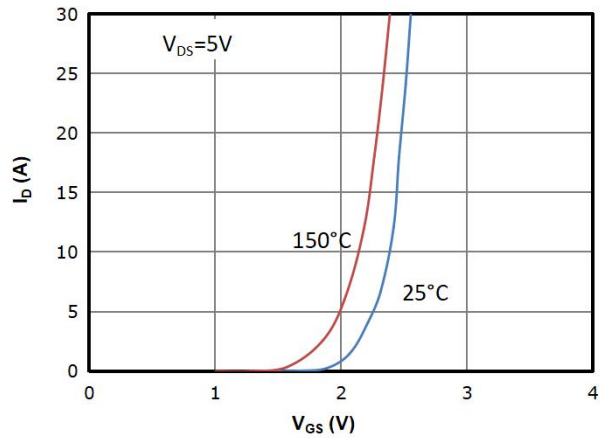


Fig 3: $R_{DS(on)}$ vs Drain Current and Gate Voltage

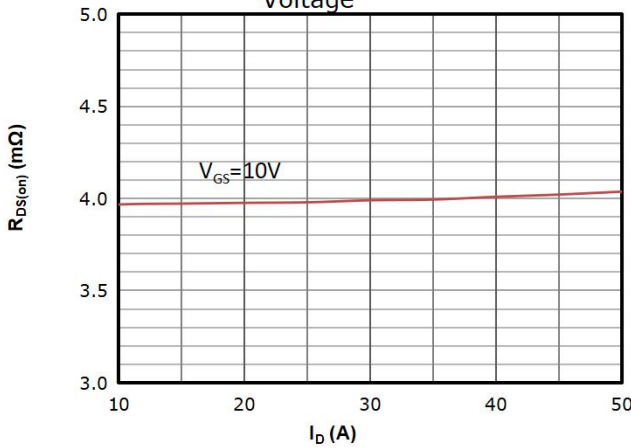


Fig 4: $R_{DS(on)}$ vs Gate Voltage

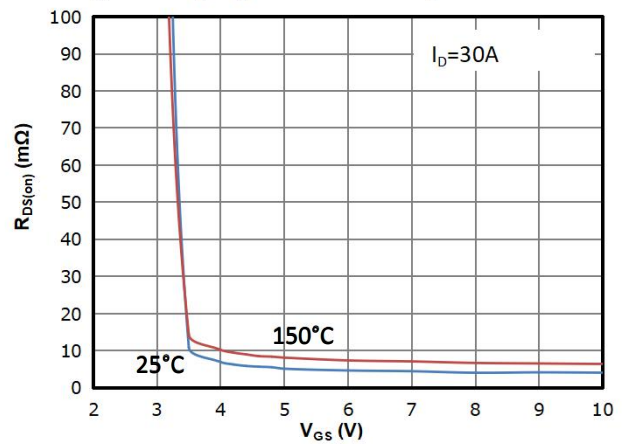


Fig 5: $R_{DS(on)}$ vs. Temperature

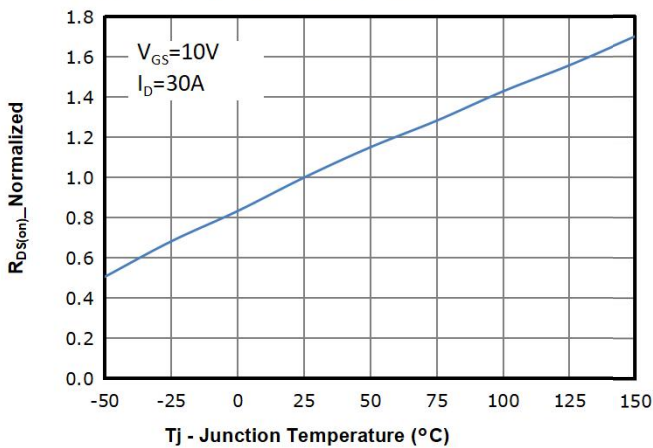


Fig 6: $V_{GS(th)}$ vs. Temperature

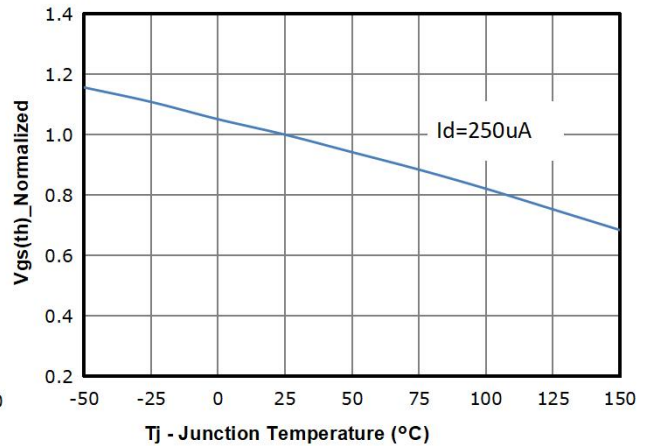


Fig 7: BVdss vs. Temperature

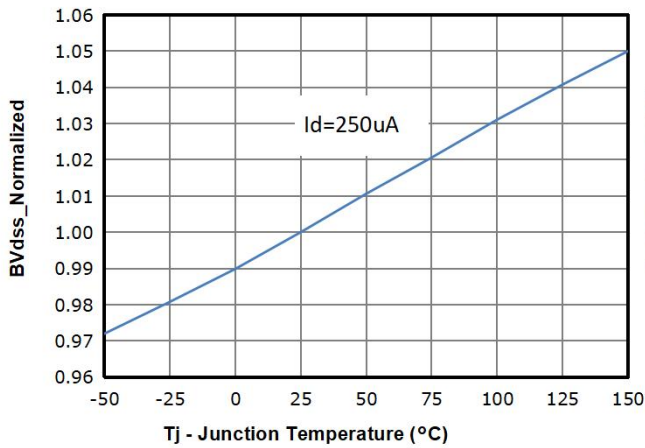


Fig 8: Capacitance Characteristics

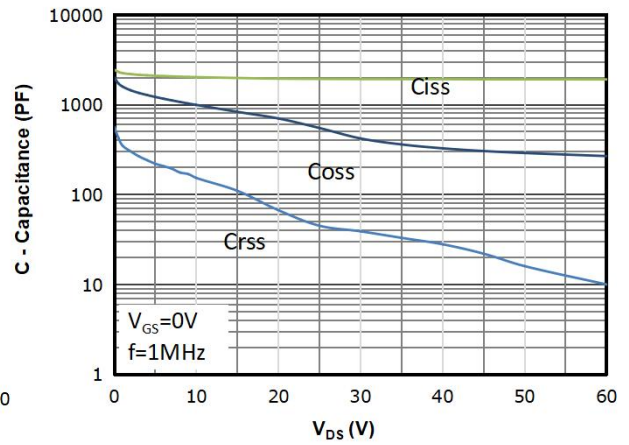


Fig 9: Gate Charge Characteristics

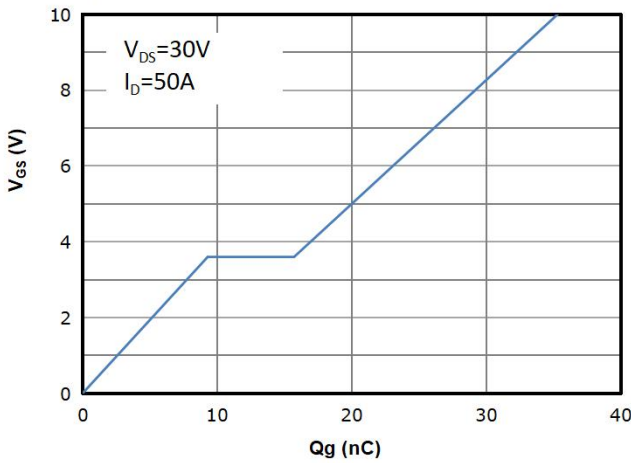


Fig 10: Body-diode Forward Characteristics

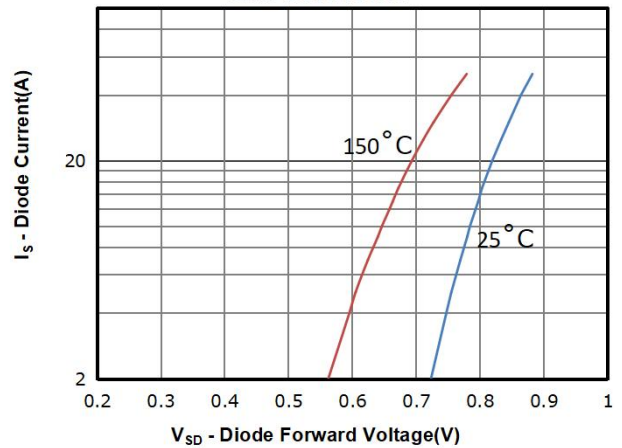


Fig 11: Power Dissipation

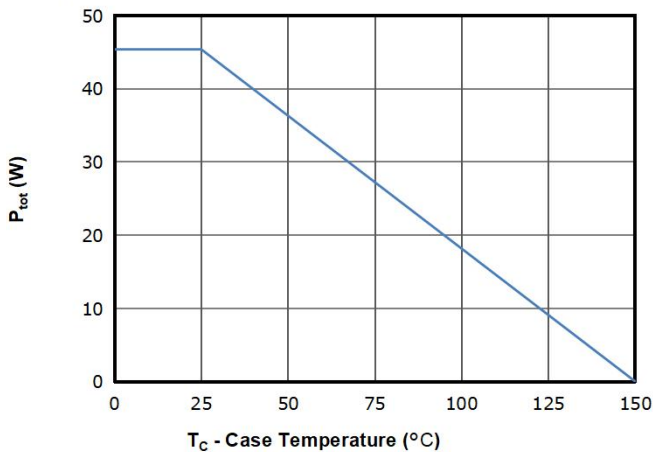


Fig 12: Drain Current Derating

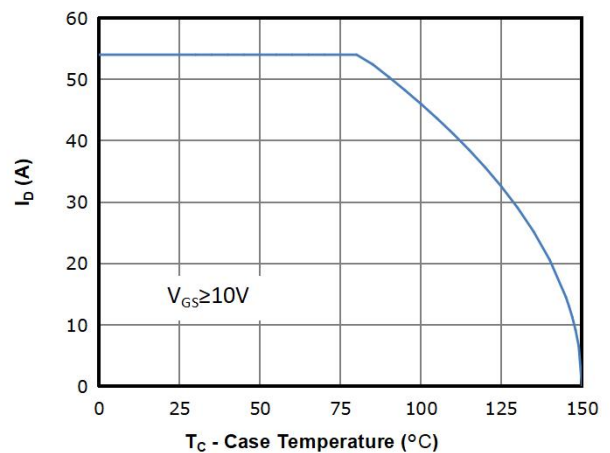


Fig 13: Safe Operating Area

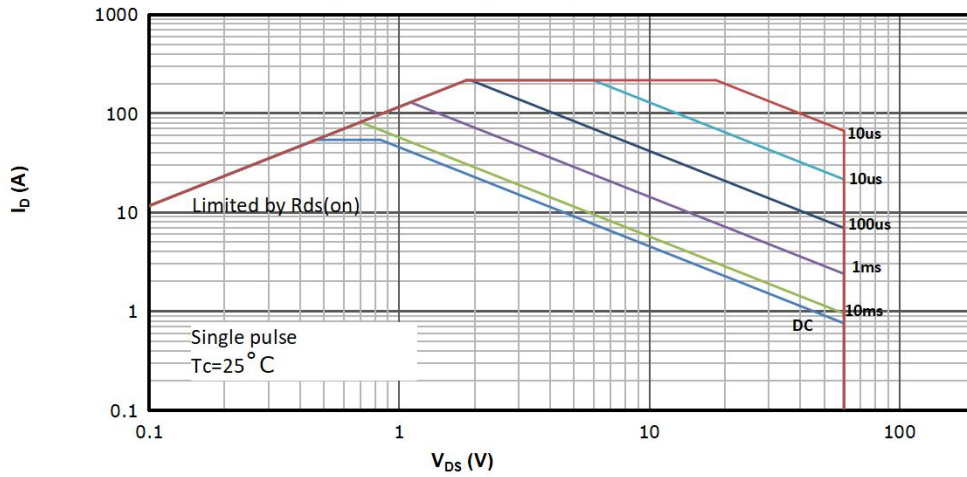
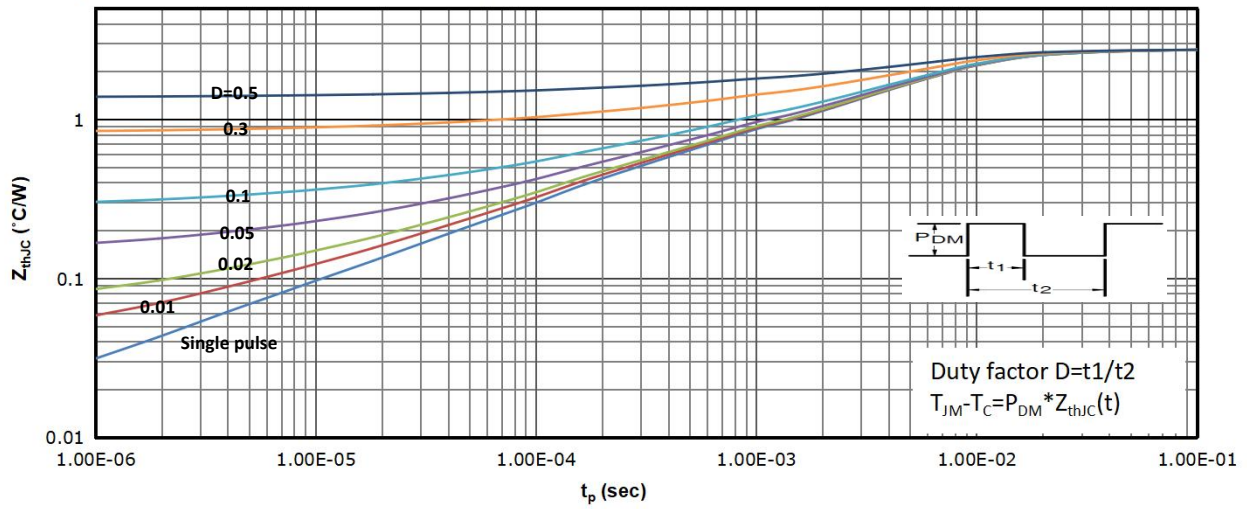


Fig 14: Max. Transient Thermal Impedance

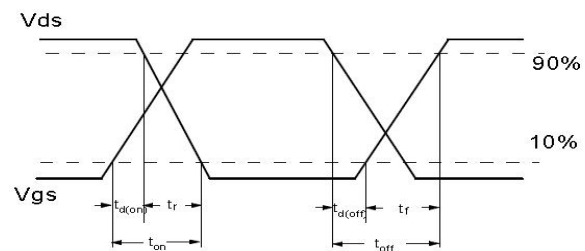


Test Circuit & Waveform

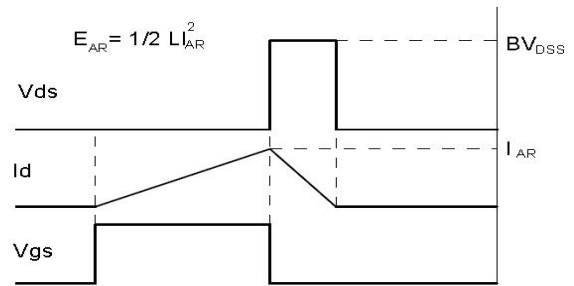
Gate Charge Test Circuit & Waveform



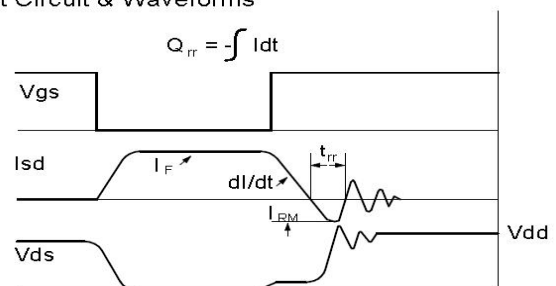
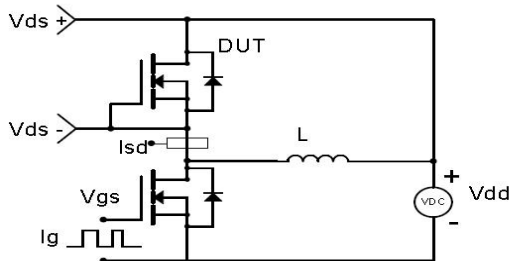
Resistive Switching Test Circuit & Waveforms



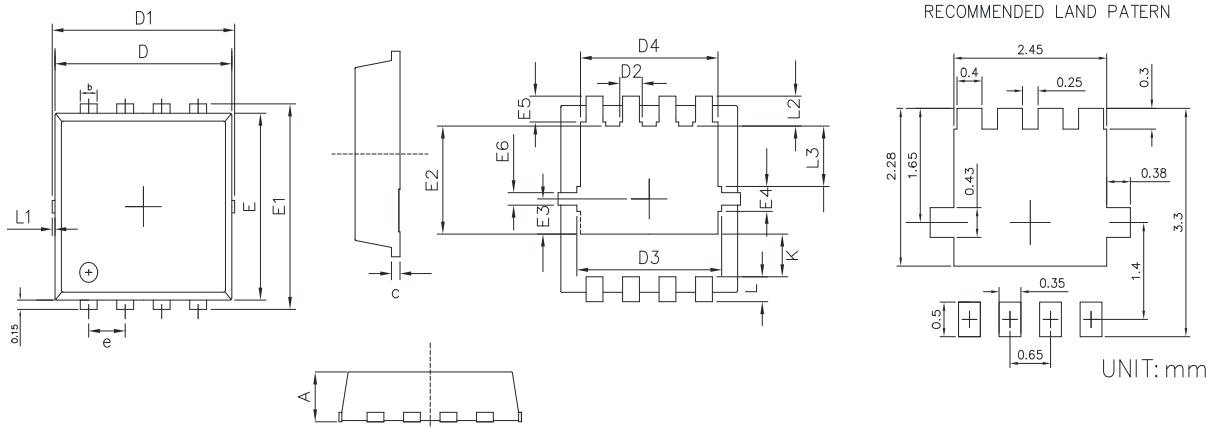
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Outline: DFN3X3



| SYMBOL | MILLIMETERS | | INCHES | |
|--------|-------------|------|--------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.70 | 1.00 | 0.028 | 0.039 |
| b | 0.24 | 0.40 | 0.009 | 0.016 |
| c | 0.10 | 0.25 | 0.004 | 0.010 |
| D | 3.00 | 3.25 | 0.118 | 0.128 |
| D1 | 3.10 | 3.50 | 0.122 | 0.138 |
| D2 | 0.30 | 0.50 | 0.012 | 0.020 |
| D3 | 2.50 | 2.70 | 0.098 | 0.106 |
| D4 | 2.35 | 2.55 | 0.093 | 0.100 |
| E | 2.90 | 3.10 | 0.114 | 0.122 |
| E1 | 3.15 | 3.45 | 0.124 | 0.136 |
| E2 | 1.65 | 1.85 | 0.065 | 0.073 |
| E3 | 0.48 | 0.68 | 0.019 | 0.027 |
| E4 | 0.23 | 0.50 | 0.009 | 0.020 |
| E5 | 0.20 | 0.40 | 0.008 | 0.016 |
| E6 | 0.08 | 0.25 | 0.003 | 0.010 |
| e | 0.55 | 0.75 | 0.022 | 0.030 |
| K | 0.52 | 0.82 | 0.020 | 0.032 |
| L | 0.25 | 0.55 | 0.010 | 0.022 |
| L1 | 0.00 | 0.10 | 0.000 | 0.004 |
| L2 | 0.28 | 0.58 | 0.011 | 0.023 |
| L3 | 0.88 | 1.08 | 0.035 | 0.043 |



Revision History

| Revision | Date | Major changes |
|----------|----------|----------------------------|
| 1.0 | 2023/9/7 | Release of Formal Version. |

Disclaimer

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